ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan-	C. Bannockt	ourn. Illinois. A	ll rights reserved u ntions.	nder both	This docum level parts, t	ent is a declaratio he declaration en	n of the substand compasses all lo	es within the manufactur wer level materials for w	rer listed ite hich the ma	em. Note: if anufacturer	the item is an as has engineering	sembly with lower responsibility.	
				Form Type Distribute									
Supplier Information													
Company name* Compa			ompany unique ID			Unique ID Authority				Response Date*			
onsemi										2025-05-12			
Contact Name Title - Conta			tact			Phone - Contact*			Email - Contact*				
Product-Env-Stewards Product Envi			nviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repre			resentative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product E			et Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	Manufacturing Site		Veight*	UOM	Unit Type	
	ES3D		UFR SMC PN 3A 200V			2025-05-12		TSCBE		32.5	mg	Each	
Manufacturing Proccess Informat	ion							-	1				
Terminal Plating / Grid Array Mat	Terminal Plating / Grid Array Material Terminal Base A		lloy J-STD-020 MSL Rating			Peak Process Body Temperature Max Time at Peak T				Temperature Number of Reflow Cycles			
Matte Tin (Sn) - annealed CU Alloy		CU Alloy	1	1		260	С	30	second	ls 3			
Comments													
evel 1 - maximum time at peak temperatu	re during sol	ldering is 10-3	0 seconds										
For more information regarding material o	omposition	please refer to	page 3										

RoHS Material Composition Declar	ation			Declaration Type *	Detailed				
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth					
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier rint a agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Iiability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In									
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.				
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the				
Supplier Digital Signature	Rastislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.798	mg	А	Lead (Pb)	7439-92-1	7c	0.1823	mg
			Supplier	Silicon (Si)	7440-21-3		3.5625	mg
			В	Nickel (Ni)	7440-02-0		0.0342	mg
			Supplier	Gold (Au)	7440-57-5		0.019	mg
Die Attach Solder	4.36	mg	Supplier	Silver (Ag)	7440-22-4		0.109	mg
			А	Lead (Pb)	7439-92-1	7a	4.033	mg
			Supplier	Tin (Sn)	7440-31-5		0.218	mg
Lead Frame	90.9231	mg	Supplier	Iron (Fe)	7439-89-6		0.1091	mg
			Supplier	Copper (Cu)	7440-50-8		90.7867	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0273	mg
Mold Compound-Black	132.0	mg		Metal Hydroxide	proprietary data		4.62	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		10.56	mg
			Supplier	Carbon Black (C)	1333-86-4		0.66	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		105.6	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		10.56	mg
Plating	1.4189	mg	Supplier	Tin (Sn)	7440-31-5		1.4189	mg